



Product Information Sheet

EPO-TEK® 921-FL

Date:	September 2017	Recommended Cure: 150°C / 1 Hour
Rev:	IV	
No. of Components:	Two	Minimum Alternative Cure(s):
Mix Ratio by Weight:	100 : 2.2	<i>May not achieve performance properties listed below</i>
Specific Gravity:	Part A: 2.39 Part B: 1.02	150°C / 5 Minutes
Pot Life:	6 Hours	120°C / 10 Minutes
Shelf Life- Bulk:	Six months at room temperature	100°C / 20 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: A two component, high Tg, electrically insulating, thermally conductive epoxy designed for thermal management applications found in semiconductor, hybrid microelectronics, PCB, and optical industries. It can be an adhesive for mounting heat sinks and substrates, a seal for many types of packages, or a thermal potting compound. It is a low viscosity version of EPO-TEK® 921.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	Part A: Grey	Part B: Amber
* Consistency:	Smooth flowing paste	
* Viscosity (23°C) @ 20 rpm:	9,000-15,000	cPs
Thixotropic Index:	2.6	
* Glass Transition Temp:	≥ 90 °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):		
Below Tg:	23	x 10 ⁻⁶ in/in°C
Above Tg:	77	x 10 ⁻⁶ in/in°C
Shore D Hardness:	87	
Lap Shear @ 23°C:	1,312	psi
Die Shear @ 23°C:	≥ 20	Kg 7,112 psi
Degradation Temp:	372	°C
Weight Loss:		
@ 200°C:	0.32	%
@ 250°C:	0.50	%
@ 300°C:	1.04	%
Suggested Operating Temperature:	< 300 °C (Intermittent)	
Storage Modulus:	1,557,705	psi
* Particle Size:	≤ 50	microns

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	1.1	W/mK
Volume Resistivity @ 23°C:	≥ 6 x 10 ¹³	Ohm-cm
Dielectric Constant (1KHz):	5.94	
Dissipation Factor (1KHz):	0.009	

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
www.epotek.com